

Glass Passivated Bridge Rectifiers

FEATURES

- Glass passivated junction
- Ideal for printed circuit board
- Reliable low cost construction
- UL Recognized File # E-326243
- Compliant to RoHS Directive 2011/65/EU and in accordance to WEEE 2002/96/EC
- Halogen-free according to IEC 61249-2-21 definition

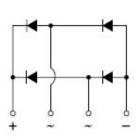
MECHANICAL DATA

Case: KBL

Molding compound, UL flammability classification rating 94V-0 Base P/N with suffix "G" on packing code - halogen-free Terminal: Matte tin plated leads, solderable per JESD22-B102 Meet JESD 201 class 1A whisker test Polarity: Polarity as marked on the body Weight: 5.6 g (approximately)









DADAMETER		KBL	KBL	KBL	KBL	KBL	KBL	KBL	Unit
PARAMETER	SYMBOL	601G	602G	603G	604G	605G	606G	607G	
Maximum repetitive peak reverse voltage	V _{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS voltage	V _{RMS}	35	70	140	280	420	560	700	V
Maximum DC blocking voltage	V _{DC}	50	100	200	400	600	800	1000	V
Maximum average forward rectified current	I _{F(AV)}	6						А	
Peak forward surge current, 8.3 ms single half sine-wave superimposed on rated load	I _{FSM}	175						А	
Rating for fusing (t<8.3ms)	l ² t				127				A ² s
Maximum instantaneous forward voltage (Note 1) I_F = 3 A I_F = 6 A	V _F	1.0 1.1							V
Maximum DC reverse current $T_J=25 \degree C$ at rated DC blocking voltage $T_J=125\degree C$	I _R	10 500				μA			
Typical thermal resistance	R _{θJL} R _{θJA}	7.5 13						^o C/W	
Operating junction temperature range	TJ	- 55 to +150							О ^о
Storage temperature range	T _{STG}	- 55 to +150							OO

Note 1: Pulse Test with PW=300µs,1% Duty Cycle



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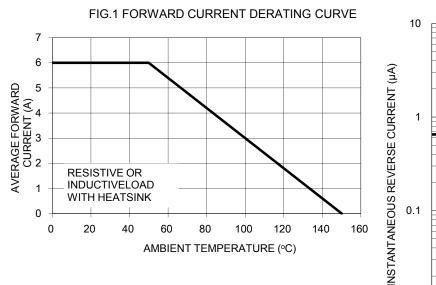
ORDERING INFORMATION						
PART NO.	PACKING CODE	GREEN COMPOUND	PACKAGE	PACKING		
		CODE				
KBL60xG (Note 1)	ТО	Suffix "G"	KBL	500 / Tray		

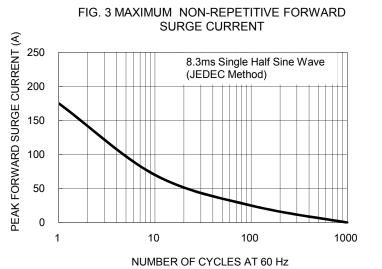
Note 1: "x" defines voltage from 50V (KBL601G) to 1000V (KBL607G)

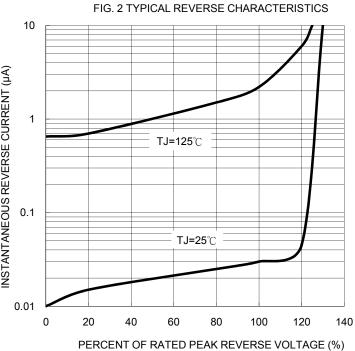
EXAMPLE							
PREFERRED P/N PART NO.		PACKING CODE	PACKING CODE GREEN COMPOUND CODE				
KBL607G T0	KBL607G	T0					
KBL607G T0G	KBL607G	TO	G	Green compound			

RATINGS AND CHARACTERISTICS CURVES

(TA=25 $^\circ\!\mathrm{C}$ unless otherwise noted)







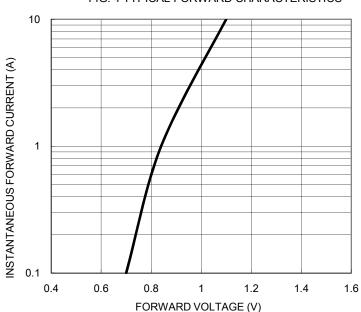
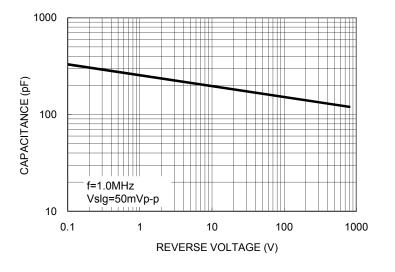


FIG. 4 TYPICAL FORWARD CHARACTERISTICS

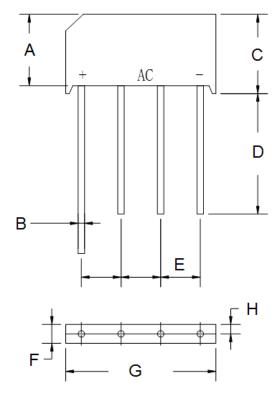


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PACKAGE OUTLINE DIMENSIONS



P/N

YWW

G

F

DIM.	Unit	(mm)	Unit (inch)		
Dilvi.	Min	Max	Min	Max	
A	13.70	14.70	0.539	0.579	
В	1.20	1.30	0.047	0.051	
С	15.20	16.30	0.598	0.642	
D	19.00	-	0.748	-	
E	4.60	5.60	0.181	0.220	
F	5.50	6.50	0.217	0.256	
G	18.50	19.50	0.728	0.768	
Н	2.1 (TYP)	0.083 (TYP)		

MARKING DIAGRAM



- = Specific Device Code
- = Green Compound
- = Date Code
- = Factory Code



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